



Customer Information Notification

202110029I : LPC2468FBD208 and LPC2478FBD208 Incorrect MSL on Packing Labels

Note: This notice is NXP Company Proprietary.

Issue Date: Nov 03, 2021 **Effective date:** Nov 04, 2021

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Management summary

The packing labels for LPC2468FBD208 and LPC2478FBD208 incorrectly specified the moisture sensitivity level (MSL) value on the packing labels.

Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input checked="" type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input type="checkbox"/> Other			

PCN Overview

Description

The packing labels for LPC2468FBD208 and LPC2478FBD208 incorrectly specified the moisture sensitivity level (MSL) value on the packing labels.

The MSL value indicated on the label has been changed to MSL 2 during date code 2142 and has been fully implemented on product with date code 2143 and later.

Devices with date code 2142 may have MSL value of 2 or 3 on the packing label.

Reason

Since October 2020, the packing labels incorrectly specified MSL 3 where the actual level for this device is MSL 2.

There is no risk to the customers since the device actual MSL is better than the value on the incorrect labels.

Identification of Affected Products

Packing Labels

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Disposition of Old Products

Existing inventory will be shipped until depleted

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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Changed Orderable Part#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
LPC2468FBD208K	935282457557	LPC2468FBD208	32-BIT ARM7	(L)QFP208	SOT459-1	RFS	No	BLM1
LPC2478FBD208K	935284069557	LPC2478FBD208	32-BIT ARM7	(L)QFP208	SOT459-1	RFS	No	BLM1